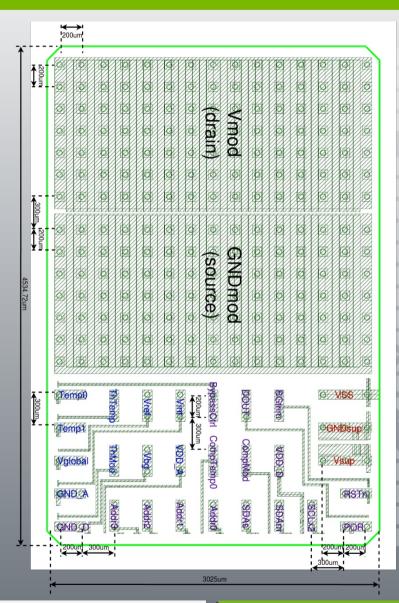
Niklaus Lehmann

PSPP Status



PSPPv4

- 40 Chips delivered in September
- At IZM for flip chip process
- Problems with fabrication of boards
 - Flex mirrored
 - Solder mask openings to small





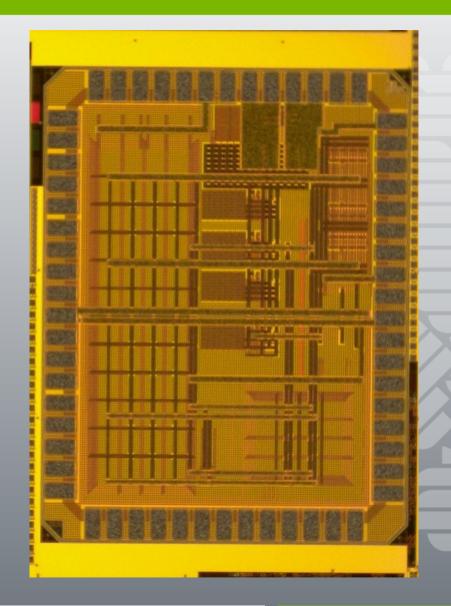
Test setups for PSPPv4

- Initial test setup ready (JK)
 - Checks basic function of chip
 - Additional setups in assembly
 - Boards for testing flexes in development
- Irradiation test setup ready (JK)
 - X-Ray irradiation for TID
- Longterm test setup at IZM (PB)
 - Bypass stress test
 - HW prototype ready, additional setups in assembly
 - SW in development



PATT

- Expected delivery of first chips soon
 - Since a while...
- Are at Novatech for dicing
 - Promised to get all ~200 chips by Christmas
- Carrier boards ready





Test setups for PATT

- Initial test setup (MG)
 - Check basic function of chip
 - HW ready and produced
 - SW development
- Irradiation setup (NL)
 - SW for SEU tests in development
 - X-Ray to be defined
- Differential communication
 - HW supports the test
 - To be specified more in details how to implement

